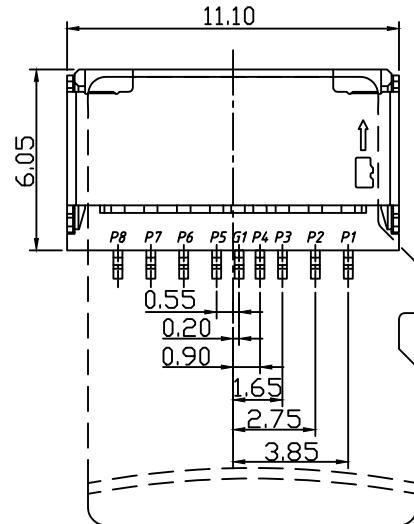
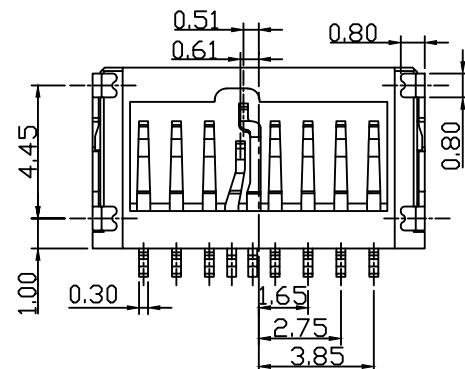


1 2 3 4 5 6 7 8 9

A



B

**Material:**

Housing:High Temperature Thermoplastic,UL94
V-0,Black.

Contact:Copper Alloy T=0.15,Plated Gold Flash on
Contact Area.

Shell:Stainless Steel T=0.20,Plated Gold Flash
on Solder Tails.

Electrical:

Rated Current:0.5A

Rated Voltage:30V

Contact Resistance:50mΩ Max.

Insulation Resistance:100MΩ Min./100V DC

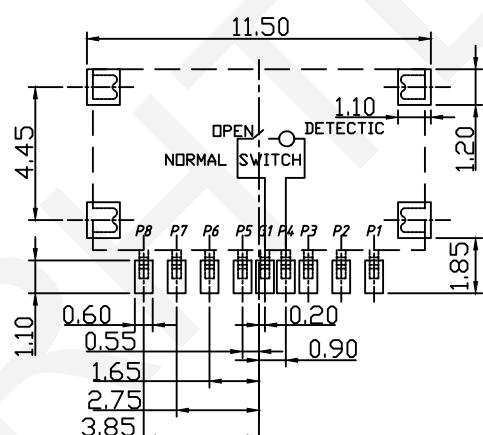
Dielectric Withstanding Voltage:100V AC

Solder ability:235 °C±5 °C,5+0.5s

Durability:5000 Cycles

Operating Condition:Temperature:-30 °C TO +80 °C

Humidity:80% R.H. Max.



RECOMMENDED PCB LAYOUT
TOLERANCE:±0.05

G1	SWITCH
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DATO
P8	DAT1
PIN NUM	DESC

E

F

G

UNITS:mm SHEET SIZE: A4 SCALE:---

0~3 3~18 18~50 50~120

±0.12 ±0.15 ±0.3 ±0.5

DRWN BY PAN

CHK'D BY FENG

APPR BY ZHAN

Micro SD Card CONN:PUSH/PULL,H1.5,
SMD with CD Pin



RHTAYF-019

RHTECP® NINGBO RHT ELECTRONIC CO.,LTD

1 2 3 4 5 6 7 8 9

A

B

C

D

E

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G